TABLE 1. PLATING SPEC

OPTION No.	PLATING SPEC
CA-H1571-1	FULL GOLD 50 μ " MIN. OVER 50 ~350 μ " ELECTROLYTIC SULFAMATE NI UNDER PLATING.
CA-H1571-2	FULL GOLD 50 μ " MIN.
CA-H1571-3	SELECTIVE GOLD POST & TOP OF EYELET 40 μ " MIN. OVER 50 ~350 μ " ELECTROLYTIC SULFAMANI UNDER PLANTING.

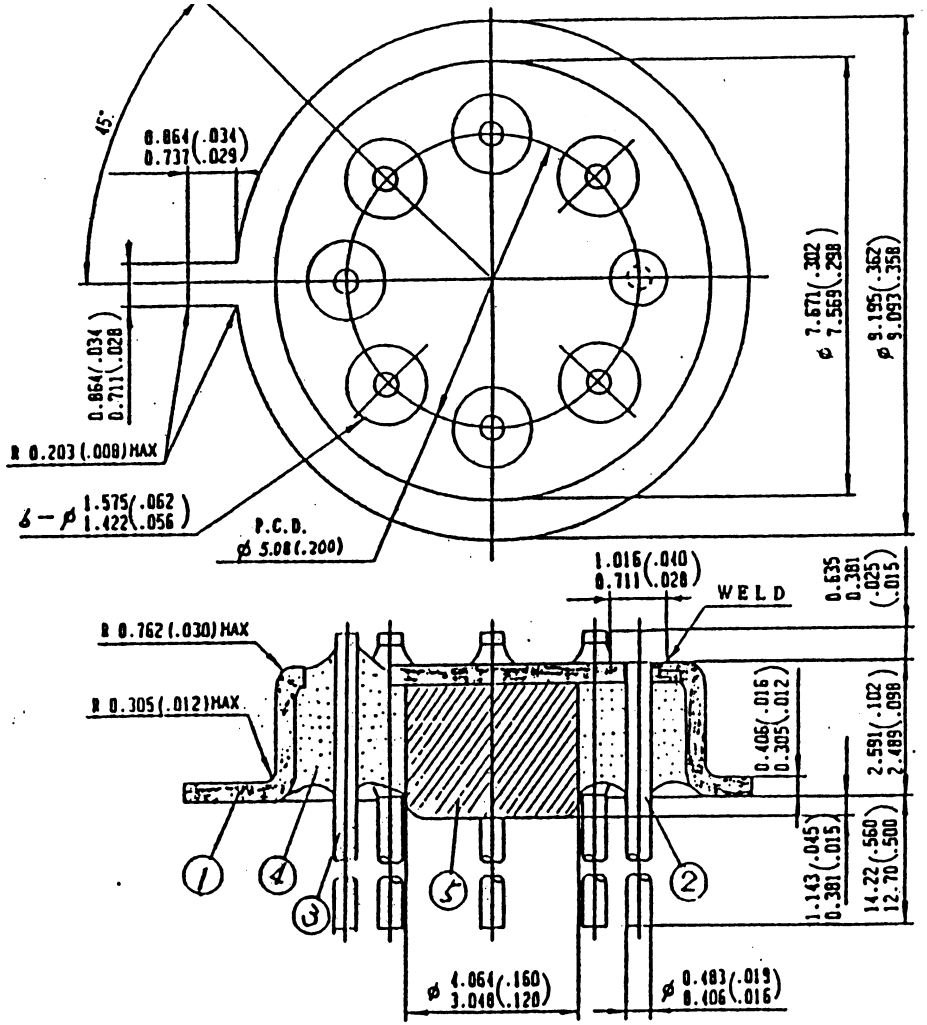
UPON REQUEST ANOTHER PLATING SPEC CAN BE AVAILABLE

NOTE 1. GOLD PLATING
(1) PLATING THICKNESS : CONTROLLED ON THE D/A AREA.

(2) MEASURING METHOD : BETASCOPE OR X-RAY FLUORESCENCE MACHINE.

2. ELECTROLYTIC NI PLATING
(1) PLATING THICKNESS : CONTROLLED ON THE LEAD.
(2) MEASURING METHOD : CROSS SECTIONING OR X-RAY FLUORESCENCE MACHINE.

HDR00549



NOTE ; SPEC
ALL PARTS MUST MEET APPLICABLE
QUALITY AND WORKMANSHIP REQUIREMENTS
AS OUTLINED IN SHINKO GENERAL SPEC
SCA-H0001

DIM. IN mm (Inch)

ITEM	DESCRIPTION	MATERIAL	QTY
5	STAND OFF	CERAMIC-GLASS	1
4	GLASS	HARD GLASS	1
3	LEAD	KOVAR	7
2	LEAD	KOVAR	1
1	EYELET	KOVAR	1

REV.	DATE	DSGN	APPR	DESCRIPTION

MATERIAL

FINISH
SEE TABLE 1.

HM0753 HM0827
HM0868 HM0772

DATE	DESIGNED	DRAWN	CHECKED	APPR'D
2.5.85	H. Ishiyama		M. Taka	H. Saito

TITLE
TO-5 HEADER LEAD

PROJ. 3RD | SCALE 10 | DRAWING NO. CA-H 1571